

ABSTRACT

A device (12) to pick up at least one disc-shaped semi-conductor wafer (11) from a container (14) of such wafers fitted on one side (15) of an aperture (13) in the transfer station (10) of a semi-conductor wafer processing plant, the device being situated on the opposite side (17) of the said aperture and the pick-up being effected through it. The device incorporates:

- A moving shutter (1) designed to move between a first, closed aperture, position and a second, open aperture, position that allows access to the inside of the container.
- A means of moving (18) this shutter between these first and second positions, the said movement taking place, at least in part, in a plane approximately parallel to the plane of the aperture.

The said device may be defined as including:

- Some means of picking up (2) at least one semi-conductor wafer (11) that is designed to enter partially within the said container below a wafer and seize this latter by its edge,
- Some means of moving (3) the said pick-ups between the said space on the second side of the aperture and the first side, and back again,
- Some means of attaching (4) the said pick-up mechanism to the shutter.

Fig. 3